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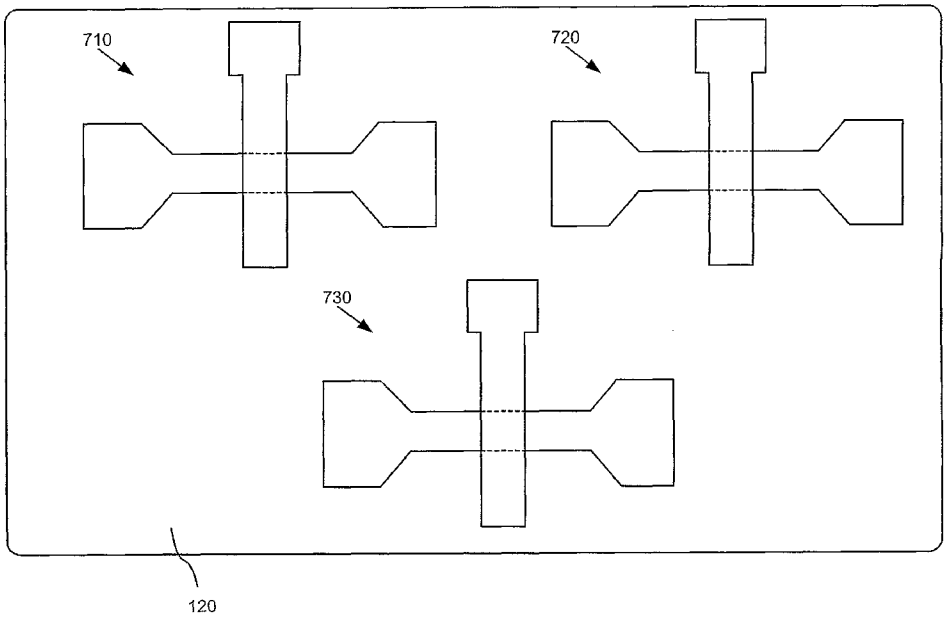
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(54) Title: VARYING CARRIER MOBILITY IN SEMICONDUCTOR DEVICES TO ACHIEVE OVERALL DESIGN GOALS



(57) Abstract: A semiconductor device (100) may include a substrate (110) and an insulating layer (120) formed on the substrate (110). A first device (710) maybe formed on the insulating layer (120), including a first fin (130). The first fin (130) maybe formed on the insulating layer (120) and may have a first fin aspect ratio. A second device (720) may be formed on the insulating layer (120), including a second fin (130). The second fin (130) may be formed on the insulating layer (120) and may have a second fin aspect ratio different from the first fin aspect ratio.

WO 2005/034207 A2

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